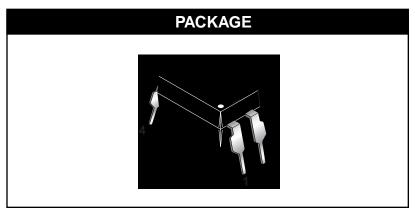
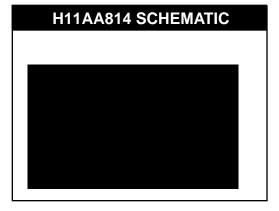


H11AA814 SERIES

H11A617 SERIES

H11A817 SERIES





DESCRIPTION

The H11AA814 Series consists of two gallium arsenide infrared emitting diodes, connected in inverse parallel, driving a single silicon phototransistor in a 4-pin dual in-line package.

The H11A617 and H11A817 Series consists of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a 4-pin dual in-line package.

FEATURES

- · Compact 4-pin package
- Current transfer ratio in selected groups:

H11AA814: 20-300% H11A817: 50-600% H11AA814A: 50-150% H11A817A: 80-160% H11A617A: 40%-80% H11A817B: 130-260% H11A617C: 100%-200% H11A817D: 300-600% H11A617D: 160%-320%

Minimum BV_{CFO} of 70V guaranteed

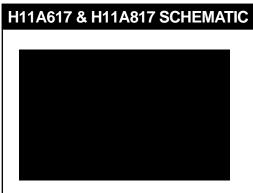
APPLICATIONS

H11AA814 Series

- · AC line monitor
- Unknown polarity DC sensor
- Telephone line interface

H11A617 and H11A817 Series

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs





H11AA814 SERIES

H11A617 SERIES

H11A817 SERIES

Parameter	Symbol	Device	Value	Units
TOTAL DEVICE				
Storage Temperature	T _{STG}	All	-55 to +150	°C
Operating Temperature	T _{OPR}	All	-55 to +100	°C
Lead Solder Temperature	T _{SOL}	All	260 for 10 sec	°C
Total Device Power Dissipation (-55°C to 50 °C)	P _D	All	200	mW
EMITTER				
Continuous Forward Current	IF	All	50	mA
Reverse Voltage	V _R	H11A617A/B/C/D H11A817/A/B/C/D	6 5	V
Forward Current - Peak (1 µs pulse, 300 pps)	I _F (pk)	All	1.0	А
LED Power Dissipation (25°C ambient) Derate above 25°C	P _D	All	100 1.33	mW mW/°C
DETECTOR				
Collector-Emitter Voltage	V _{CEO}	All	70	V
Emitter-Collector Voltage	V _{ECO}	H11AA814/A H11A617A/B/C/D H11A817/A/B/C/D	6 7 6	V
Continuous Collector Current	I _C	All	50	mA
Detector Power Dissipation (25°C ambient)	P _D	All	150	mW
Derate above 25°C			2.0	mW/°C

ELECTRICAL CHARACTERISTICS (T_A = 25°C Unless otherwise specified.) INDIVIDUAL COMPONENT CHARACTERISTICS **Parameter Test Conditions Symbol Device** Min Typ* Max Unit **EMITTER** $(I_F = 60 \text{ mA})$ 1.35 H11A617A/B/C/D 1.65 $(I_F = 20 \text{ mA})$ V_{F} H11A817/A/B/C/D 1.2 1.5 V Input Forward Voltage $(I_F = \pm 20 \text{ mA})$ H11AA814/A 1.2 1.5 $(V_R = 6.0 V)$ H11A617A/B/C/D Reverse Leakage Current I_R .001 10 μΑ $(V_R = 5.0 V)$ H11A817/A/B/C/D DETECTOR Collector-Emitter Breakdown $(I_C = 1.0 \text{ mA}, I_F = 0)$ BV_{CEO} 70 100 V ALL Voltage H11AA814/A 6 Emitter-Collector Breakdown $(I_F = 100 \mu A, I_F = 0)$ BV_{ECO} H11A617A/B/C/D 7 10 V Voltage H11A817/A/B/C/D H11AA814/A, H11A817/A/B/C/D, 100 $(V_{CE} = 10V, I_F = 0)$ Collector-Emitter Dark Current H11A617C/D 1 nΑ ICEO H11A617A/B 50 Collector-Emitter Capacitance $(V_{CE} = 0 V, f = 1 MHz)$ C_{CE} ALL 8 рF

^{*}Typical values at $T_A = 25$ °C.



H11AA814 SERIES

H11A617 SERIES

H11A817 SERIES

DC Characteristic	Test Conditions	Symbol	Device	Min	Тур*	Max	Unit
	$(I_F = \pm 1 \text{ mA}, V_{CE} = 5 \text{ V}) \text{ (note 1)}$		H11AA814	20		300	%
	$(I_F = \pm 1 \text{ mA}, V_{CE} = 5 \text{ V}) \text{ (note 1)}$		H11AA814A	50		150	%
	(I _F = 10 mA, V _{CE} = 5 V) (note 1)	CTR	H11A617A	40		80	%
			H11A617B	63		125	%
			H11A617C	100		200	%
			H11A617D	160		320	%
Current Transfer Ratio	(I _F = 5 mA, V _{CE} = 5 V) (note 1)		H11A817	50		600	%
			H11A817A	80		160	%
			H11A817B	130		260	%
			H11A817C	200		400	%
			H11A817D	300		600	%
	(I _F = 1 mA, V _{CE} = 5 V) (note 1)		H11A617A	13			%
			H11A617B	22			%
			H11A617C	34			%
			H11A617D	56			%
0.11	$(I_C = 1 \text{ mA}, I_F = \pm 20 \text{ mA})$		H11AA814/A			0.2	
Collector-Emitter Saturation Voltage	$(I_C = 2.5 \text{ mA}, I_F = 10 \text{ mA})$	V _{CE (SAT)}	H11A617A/B/C/D			0.4	V
	$(I_C = 1 \text{ mA}, I_F = 20 \text{ mA})$		H11A817/A/B/C/D			0.2	
AC Characteristic							
Rise Time	$(I_C = 2 \text{ mA}, V_{CE} = 2 \text{ V}, R_L = 100\Omega) \text{ (note 2)}$	t _r	ALL		2.4	18	μs
Fall Time	$(I_C = 2 \text{ mA}, V_{CE} = 2 \text{ V}, R_L = 100\Omega) \text{ (note 2)}$	t _f	ALL		2.4	18	μs

ISOLATION CHARACTERISTICS						
Characteristic	Test Conditions	Symbol	Min	Тур*	Max	Units
Input-Output Isolation Voltage (note 3)	f = 60Hz, t = 1 min	V _{ISO}	5300			Vac(rms)
Isolation Resistance	(V _{I-O} = 500 VDC)	R _{ISO}	10 ¹¹			Ω
Isolation Capacitance	$(V_{I-O} = 0, f = 1 \text{ MHz})$	C _{ISO}		0.5		pf

^{*}Typical values at $T_A = 25$ °C.

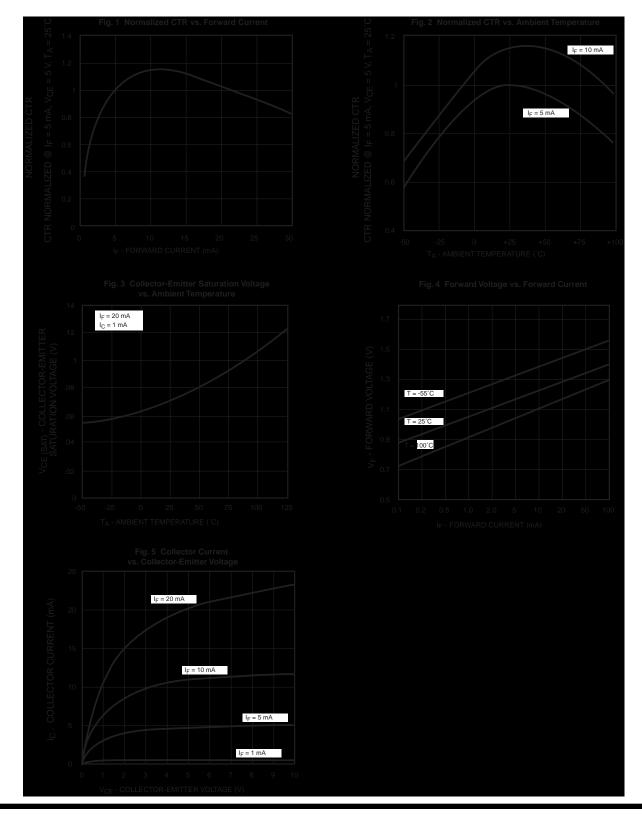
NOTES

- 1. Current Transfer Ratio (CTR) = $I_C/I_F \times 100\%$.
- 2. For test circuit setup and waveforms, refer to Figure 8.
- 3. For this test, Pins 1 and 2 are common, and Pins 3 and 4 are common.

H11AA814 SERIES

H11A617 SERIES

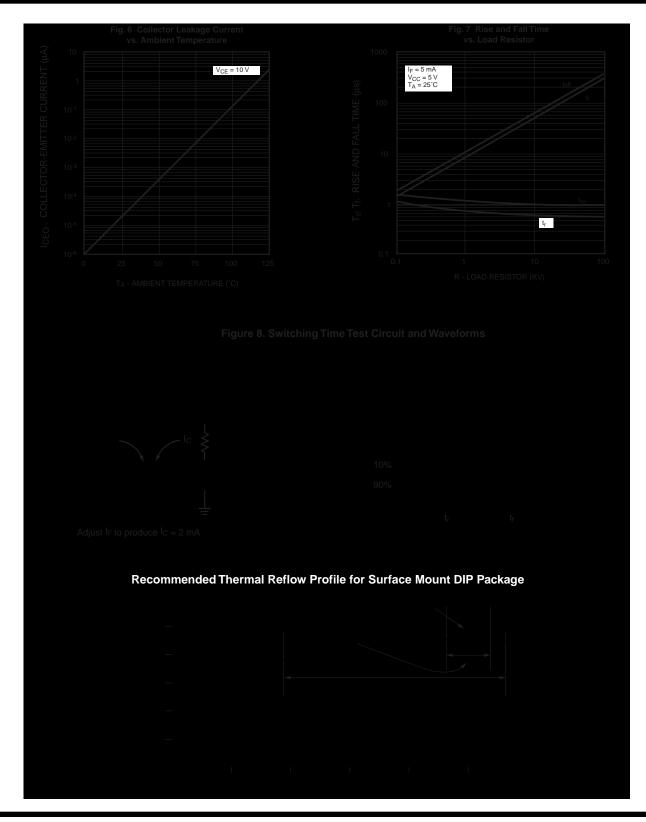
H11A817 SERIES



H11AA814 SERIES

H11A617 SERIES

H11A817 SERIES

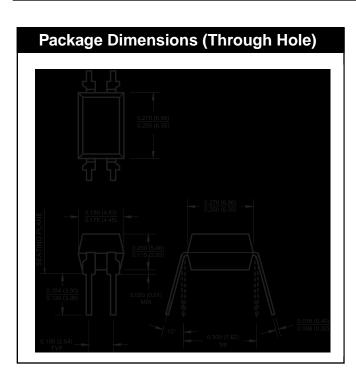


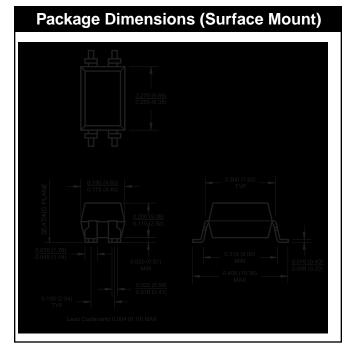


H11AA814 SERIES

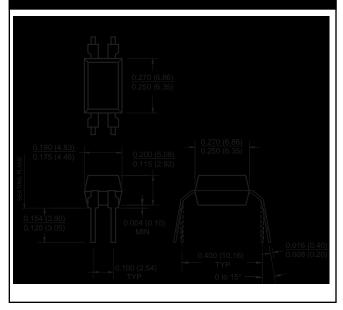
H11A617 SERIES

H11A817 SERIES





Package Dimensions (0.4" Lead Spacing)



0.070 (1.78) 0.060 (1.52) 0.100 (2.54) 0.295 (7.49) 0.415 (10.54)

Footprint Dimensions (Surface Mount)

NOTEAll dimensions are in inches (millimeters)



H11AA814 SERIES

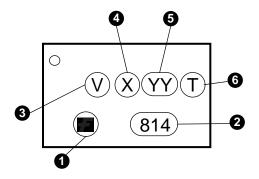
H11A617 SERIES

H11A817 SERIES

ORDERING INFORMATION

Option	Order Entry Identifier	Description
S	.S	Surface Mount Lead Bend
SD	.SD	Surface Mount; Tape and reel
W	.W	0.4" Lead Spacing
300	.300	VDE 0884
300W	.300W	VDE 0884, 0.4" Lead Spacing
3S	.3\$	VDE 0884, Surface Mount
3SD	.3SD	VDE 0884, Surface Mount, Tape & Reel

MARKING INFORMATION



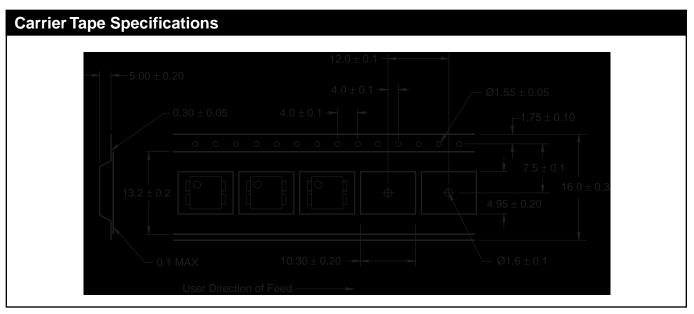
Definitions				
1	Fairchild logo			
2	Device number			
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)			
4	One digit year code			
5	Two digit work week ranging from '01' to '53'			
6	Assembly package code			



H11AA814 SERIES

H11A617 SERIES

H11A817 SERIES



NOTE

All dimensions are in millimeters



H11AA814 SERIES

H11A617 SERIES

H11A817 SERIES

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